

September 1983 Revised February 1999

# MM74HC175 Quad D-Type Flip-Flop With Clear

### **General Description**

The MM74HC175 high speed D-type flip-flop with complementary outputs utilizes advanced silicon-gate CMOS technology to achieve the high noise immunity and low power consumption of standard CMOS integrated circuits, along with the ability to drive 10 LS-TTL loads.

Information at the  $\underline{D}$  inputs of the MM74HC175 is transferred to the Q and  $\overline{Q}$  outputs on the positive going edge of the clock pulse. Both true and complement outputs from each flip flop are externally available. All four flip-flops are controlled by a common clock and a common CLEAR. Clearing is accomplished by a negative pulse at the CLEAR input. All four Q outputs are cleared to a logical "0" and all four  $\overline{Q}$  outputs to a logical "1."

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

### **Features**

- Typical propagation delay: 15 ns
- Wide operating supply voltage range: 2-6V
- Low input current: 1 µA maximum
- Low quiescent supply current: 80 µA maximum (74HC)
- High output drive current: 4 mA minimum (74HC)

### **Ordering Code:**

Order Number	Package Number	Package Description
MM74HC175M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
MM74HC175SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC175MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC175N	N16E	16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### **Connection Diagram**

## 

#### **Truth Table**

(Each Flip-Flop)							
ı	nputs		Outputs				
Clear	Clock	D	Q	Q			
L	X	Х	L	Н			
Н	1	Н	Н	L			
Н	1	L	L	Н			
Н	L	Х	$Q_0$	$\overline{Q}_0$			

- H = HIGH Level (steady state)
- L = LOW Level (steady state)
- X = Irrelevant
- Transition from LOW-to-HIGH level
- $\mathbf{Q}_0 = \text{The level of Q}$  before the indicated steady-state input conditions were established

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### **Absolute Maximum Ratings**(Note 1) (Note 2)

Storage Temperature Range ( $T_{STG}$ ) Power Dissipation ( $P_D$ )

 (Note 3)
 600 mW

 S.O. Package only
 500 mW

-65°C to +150°C

Lead Temperature  $(T_L)$ 

(Soldering 10 seconds) 260°C

### Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )	2	6	V
DC Input or Output Voltage			
$(V_{IN}, V_{OUT})$	0	$V_{CC}$	V
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
$V_{CC} = 4.5V$		500	ns
$V_{CC} = 6.0V$		400	ns
Note 1: Absolute Maximum Patings are those	a values	heyond wh	ich dam-

**Note 1:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: – 12 mW/°C from 65°C to 85°C.

### DC Electrical Characteristics (Note 4)

Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units	
			vcc	Тур		Guaranteed L	imits	Units	
V <sub>IH</sub>	Minimum HIGH Level		2.0V		1.5	1.5	1.5	V	
	Input Voltage		4.5V		3.15	3.15	3.15	V	
			6.0V		4.2	4.2	4.2	V	
V <sub>IL</sub>	Maximum LOW Level		2.0V		0.5	0.5	0.5	V	
	Input Voltage		4.5V		1.35	1.35	1.35	V	
			6.0V		1.8	1.8	1.8	V	
V <sub>OH</sub>	Minimum HIGH Level	$V_{IN} = V_{IH}$ or $V_{IL}$							
	Output Voltage	$ I_{OUT}  \le 20 \ \mu A$	2.0V	2.0	1.9	1.9	1.9	V	
			4.5V	4.5	4.4	4.4	4.4	V	
			6.0V	6.0	5.9	5.9	5.9	V	
		$V_{IN} = V_{IH}$ or $V_{IL}$							
		$ I_{OUT}  \le 4.0 \text{ mA}$	4.5V	4.2	3.98	3.84	3.7	V	
		$ I_{OUT}  \le 5.2 \text{ mA}$	6.0V	5.7	5.48	5.34	5.2	V	
V <sub>OL</sub>	Maximum LOW Level	$V_{IN} = V_{IH}$ or $V_{IL}$							
	Output Voltage	$ I_{OUT}  \le 20 \ \mu A$	2.0V	0	0.1	0.1	0.1	V	
			4.5V	0	0.1	0.1	0.1	V	
			6.0V	0	0.1	0.1	0.1	V	
		$V_{IN} = V_{IH}$ or $V_{IL}$							
		$ I_{OUT}  \le 4.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V	
		$ I_{OUT}  \le 5.2 \text{ mA}$	6.0V	0.2	0.26	0.33	0.4	V	
I <sub>IN</sub>	Maximum Input	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μΑ	
	Current								
I <sub>CC</sub>	Maximum Quiescent	$V_{IN} = V_{CC}$ or GND	6.0V		8	80	160	μА	
	Supply Current	$I_{OUT} = 0 \mu A$							

Note 4: For a power supply of 5V  $\pm$ 10% the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5V$  and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

### **AC Electrical Characteristics**

 $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 15$  pF,  $t_r = t_f = 6$  ns

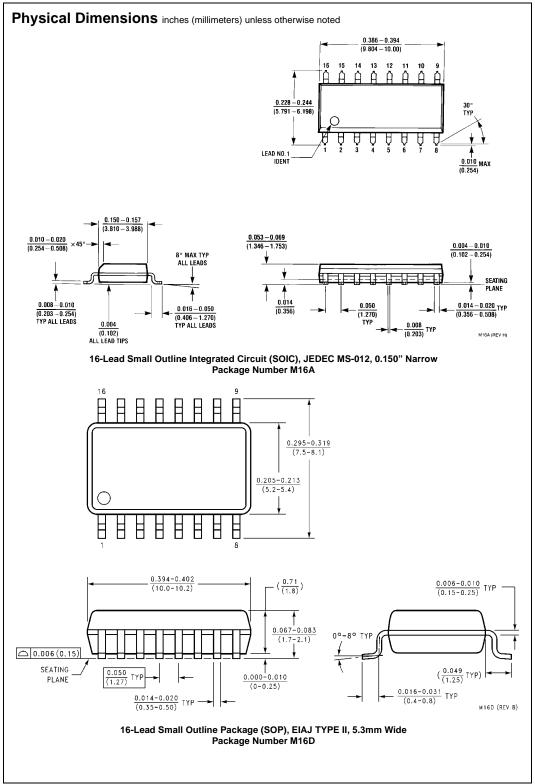
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
f <sub>MAX</sub>	Maximum Operating		60	35	MHz
	Frequency				
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		15	25	ns
	Delay, Clock to Q or Q				
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		13	21	ns
	Delay, Reset to Q or Q				
t <sub>REC</sub>	Minimum Removal			20	ns
	Time, Clear to Clock				
t <sub>S</sub>	Minimum Setup Time, Data to Clock			20	ns
t <sub>H</sub>	Minimum Hold Time, Data from Clock			0	ns
t <sub>W</sub>	Minimum Pulse Width, Clock or Clear		10	16	ns

### **AC Electrical Characteristics**

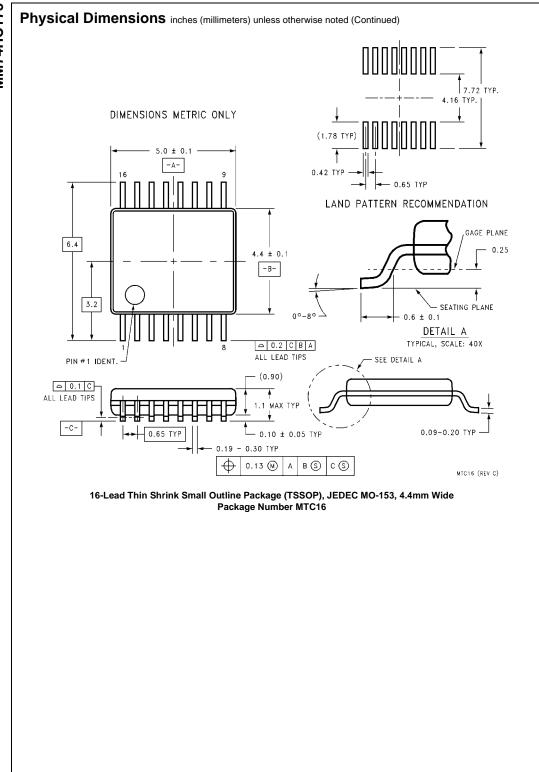
 $\rm V_{CC} = 2.0V$  to 6.0V,  $\rm C_L = 50$  pF,  $\rm t_f = t_f = 6$  ns (unless otherwise specified)

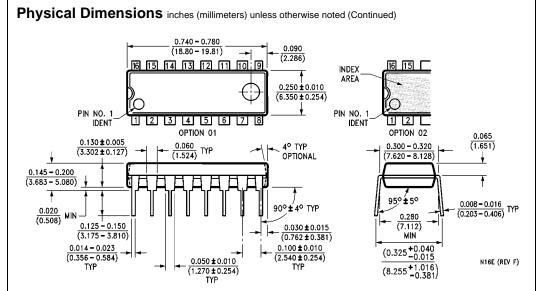
Symbol	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
Cymbol				Тур		Guaranteed Limits		
f <sub>MAX</sub>	Maximum Operating		2.0V	12	6	5	4	MHz
	Frequency		4.5V	60	30	24	20	MHz
			6.0V	70	35	28	24	MHz
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		2.0V	80	150	190	225	ns
	Delay, Clock to Q or Q		4.5V	15	30	38	45	ns
			6.0V	13	26	32	38	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		2.0V	64	125	158	186	ns
	Delay, Reset to Q or Q		4.5V	14	25	32	37	ns
			6.0V	12	21	27	32	ns
t <sub>REM</sub>	Minimum Removal Time		2.0V		100	125	150	ns
	Clear to Clock		4.5V		20	25	30	ns
			6.0V		17	21	25	ns
t <sub>S</sub>	Minimum Setup Time		2.0V		100	125	150	ns
	Data to Clock		4.5V		20	25	30	ns
			6.0V		17	21	25	ns
t <sub>H</sub>	Minimum Hold Time		2.0V		0	0	0	ns
	Data from Clock		4.5V		0	0	0	ns
			6.0V		0	0	0	ns
t <sub>W</sub>	Minimum Pulse Width		2.0V	30	80	100	120	ns
	Clear or Clock		4.5V	9	16	20	24	ns
			6.0V	8	14	17	20	ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and		2.0V		1000	1000	1000	ns
	Fall Time		4.5V		500	500	500	ns
			6.0V		400	400	400	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum		2.0V	30	75	95	110	ns
	Output Rise and		4.5V	9	15	19	22	ns
	Fall Time		6.0V	8	13	16	19	ns
C <sub>PD</sub>	Power Dissipation	(per package)		150				pF
	Capacitance (Note 5)	(per package)						
C <sub>IN</sub>	Maximum Input			5	10	10	10	pF
	Capacitance							

 $\textbf{Note 5: } C_{PD} \text{ determines the no load dynamic power consumption, } P_D = C_{PD} \ V_{CC}^2 \\ \text{$I_{CC}$} \ V_{CC}, \text{ and the no load dynamic current consumption, } \\ I_S = C_{PD} \ V_{CC} \\ \text{$I_{CC}$} \ V_{CC}, \text{ and the no load dynamic current consumption, } \\ I_S = C_{PD} \ V_{CC} \\ \text{$I_{CC}$} \ V_{CC}, \text{ and the no load dynamic current consumption, } \\ I_S = C_{PD} \ V_{CC} \\ \text{$I_{CC}$} \ V_{CC}, \text{ and the no load dynamic current consumption, } \\ I_S = C_{PD} \ V_{CC} \\ \text{$I_{CC}$} \ V_{CC}, \text{ and } \\$ 



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16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N16E

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